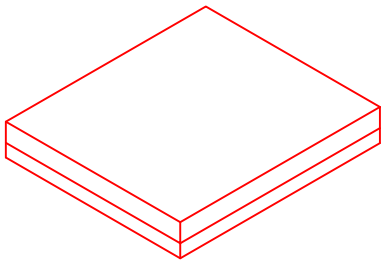
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06111	05/06/99	E.B	MCN
01	REMOVE L-FIDS. FROM P/O, DCN C07080	10/27/99	LPETE	LMACK
02	ADDED THE 160 BALLS PER DCN # A54925	05/06/02	LSMIN	LSMIN
03	CORRECTED TYPOS PER DCN # A55221	06/04/02	LSMIN	LSMIN



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 196.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 14 X 14.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.50.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ± 0.1; X.XX ± 0.05; X.XXX ± 0.030
ANGULAR: ± 1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DRAWN M. NOBLES	04/19/99
CHECKED J. MICKSCH	04/29/99
APPROVED H. BUENAOBRA	04/30/99
RELEASED G. SCHULTZ	05/06/99

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - CTBGA 132/160,
8.00mm X 8.00mm, 2 LAYER,
0.50mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	75428	03

STRIP DWG NUMBER/REV	SCALE	SHEET
N/A	NONE	1 OF 3

FORM NO: MBFLAM1A1.DWG